

# PATENT ASSIGNMENT

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT																						
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT																						
<b>CONVEYING PARTY DATA</b>																							
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th style="width: 30%;">Execution Date</th> </tr> </thead> <tbody> <tr><td>Shiho Moriai</td><td>08/12/2011</td></tr> <tr><td>Tsuyoshi Masato</td><td>07/29/2011</td></tr> <tr><td>Shinichi Uesaka</td><td>08/13/2011</td></tr> <tr><td>Atsushi Ozawa</td><td>07/29/2011</td></tr> <tr><td>Masanobu Katagi</td><td>08/10/2011</td></tr> <tr><td>Tomoyuki Ono</td><td>08/11/2011</td></tr> <tr><td>Kazuhito Tsuchida</td><td>08/08/2011</td></tr> <tr><td>Shin Hotta</td><td>07/29/2011</td></tr> <tr><td>Kazuo Nakamura</td><td>07/29/2011</td></tr> <tr><td>Kentaro Marutani</td><td>08/08/2011</td></tr> </tbody> </table>		Name	Execution Date	Shiho Moriai	08/12/2011	Tsuyoshi Masato	07/29/2011	Shinichi Uesaka	08/13/2011	Atsushi Ozawa	07/29/2011	Masanobu Katagi	08/10/2011	Tomoyuki Ono	08/11/2011	Kazuhito Tsuchida	08/08/2011	Shin Hotta	07/29/2011	Kazuo Nakamura	07/29/2011	Kentaro Marutani	08/08/2011
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<table border="1" style="width: 100%; border-collapse: collapse;"> <tr><td style="width: 20%;"><b>Name:</b></td><td>Sony Corporation</td></tr> <tr><td><b>Street Address:</b></td><td>1-7-1 Konan, Minato-ku</td></tr> <tr><td><b>City:</b></td><td>Tokyo</td></tr> <tr><td><b>State/Country:</b></td><td>JAPAN</td></tr> </table>		<b>Name:</b>	Sony Corporation	<b>Street Address:</b>	1-7-1 Konan, Minato-ku	<b>City:</b>	Tokyo	<b>State/Country:</b>	JAPAN														
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<b>PROPERTY NUMBERS Total: 1</b>																							
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<b>CORRESPONDENCE DATA</b>																							
<p>Fax Number: (312)827-8185</p> <p>Phone: 3128074310</p> <p>Email: <a href="mailto:chicago.patents@klgates.com">chicago.patents@klgates.com</a></p> <p><i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i></p> <p>Correspondent Name: Thomas C. Basso</p> <p>Address Line 1: P.O. Box 1135</p> <p>Address Line 2: K&amp;L Gates LLP</p>																							

CH \$40.00 13230148

**501665971**

**PATENT**  
**REEL: 026952 FRAME: 0466**

Address Line 4: Chicago, ILLINOIS 60690-1135

ATTORNEY DOCKET NUMBER:

3712174-02882

NAME OF SUBMITTER:

Thomas C. Basso

Total Attachments: 3

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**ASSIGNMENT**

WHEREAS, I, as below named inventor, residing at the addresses stated next to our names, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

POWER SUPPLY DEVICE

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, SONY CORPORATION, a Japanese corporation, with offices at 1-7-1 Konan, Minato-ku, Tokyo, Japan (hereinafter referred to as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest therein;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any release or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: 13/230,148, Filing Date: September 12, 2011.

This assignment executed on the dates indicated below.

SHIHO MORIAI

Name of first or sole inventor  
KANAGAWA JAPAN

Residence of first or sole inventor  
*Shiho Moriai*

Signature of first or sole inventor

Execution date of U.S. Patent Application  
August 12, 2011

Date of this assignment

TSUYOSHI MASATO

Name of second inventor  
KANAGAWA JAPAN

Residence of second inventor  
*Tsuyoshi Masato*

Signature of second inventor

Execution date of U.S. Patent Application

Date of this assignment  
July 29, 2011

SHINICHI UESAKA

Name of third inventor  
KANAGAWA JAPAN

Residence of third inventor  
*Shinichi Uesaka*

Signature of third inventor

Execution date of U.S. Patent Application

Date of this assignment  
August 15, 2011

**PATENT**

**REEL: 026952 FRAME: 0468**

# ADDITIONAL INVENTOR(S)

Attorney Docket No. 3712174-2862  
SONY Ref. No.:S1P1711U500

ATSUSHI OZAWA

Name of fourth inventor  
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Residence of fourth inventor

Signature of fourth inventor

Execution date of U.S. Patent Application

Date of this assignment

MASANORU KATAGI

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Date of this assignment

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Signature of sixth inventor

Execution date of U.S. Patent Application

Date of this assignment

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Signature of seventh inventor

Execution date of U.S. Patent Application

Date of this assignment

SHIN HOTTA

Name of eighth inventor  
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Signature of eighth inventor

Execution date of U.S. Patent Application

Date of this assignment

KAZUO NAKAMURA

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Residence of ninth inventor

Signature of ninth inventor

Execution date of U.S. Patent Application

Date of this assignment

PATENT

REEL: 026952 FRAME: 0469

# ADDITIONAL INVENTOR(S)

Attorney Docket No. 3712174-2882  
SONY Ref. No.: S11P1711US00

KENTARO MARUTANI	
Name of tenth inventor	Execution date of U.S. Patent Application
KANAGAWA JAPAN	
Residence of tenth inventor	
<del>Kentaro Marutani</del> <i>Kentaro Marutani</i>	<del>August 8, 2011</del> <i>August 8, 2011</i>
Signature of tenth inventor	Date of this assignment
Name of eleventh inventor	Execution date of U.S. Patent Application
Residence of eleventh inventor	
Signature of eleventh inventor	Date of this assignment
Name of twelfth inventor	Execution date of U.S. Patent Application
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Name of thirteen inventor	Execution date of U.S. Patent Application
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Signature of fifteen inventor	Date of this assignment

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RECORDED: 09/21/2011